

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L10	5319	(451/41,56).CCLS	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2009/06/05 10:49
L11	2264	(451/526-539).CCLS	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2009/06/05 10:49
L12	130	10 and pad and radial and groove and volume	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2009/06/05 10:50
L13	98	11 and pad and radial and groove and volume	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2009/06/05 10:58
L14	65	11 and pad and groove and volume same area	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2009/06/05 11:01
L15	79	10 and pad and groove and volume same area	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2009/06/05 11:12
L16	3635	(451/28,57,59,60).CCLS	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2009/06/05 11:16
L17	38	16 and pad and radial and groove and volume	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2009/06/05 11:17
L18	33	16 and pad and groove and volume same area	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2009/06/05 11:19
L19	0	((circular with substrate) and groove and (radial with pattern) and (volume with groove) and (area with substrate)).clm.	US-PGPUB; USPAT	OR	ON	2009/06/05 11:22
L20	0	((circular with substrate) and groove and (radial with pattern) and (volume same area)).clm.	US-PGPUB; USPAT	OR	ON	2009/06/05 11:23
L21	12	16 and pad and groove same volume	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2009/06/05 11:25
L22	59	11 and pad and groove same volume	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2009/06/05 11:27

L23	49	10 and pad and groove same volume	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2009/06/05 11:28
L24	79	10 and pad and groove and volume same area	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2009/06/05 11:30
L25	65	11 and pad and groove and volume same area	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2009/06/05 11:32
L26	403	10 and pad and groove and below with (substrate or wafer)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2009/06/05 11:34
L27	96	10 and pad and groove same below same (substrate or wafer)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2009/06/05 11:36
L28	73	11 and pad and groove same below same (substrate or wafer)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2009/06/05 11:39
L29	36	16 and pad and groove same below same (substrate or wafer)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2009/06/05 11:40
L30	0	(polish\$3 and substrate and groove and (radial with pattern) and volume and (below with substrate)).dm.	US-PGPUB; USPAT	OR	ON	2009/06/05 11:43

6/ 5/ 2009 12:13:35 PM

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